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#### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

## Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	24MHz
Connectivity	I <sup>2</sup> C, IrDA, LINbus, Microwire, SmartCard, SPI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, CapSense, LCD, LVD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4024azi-s413t

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



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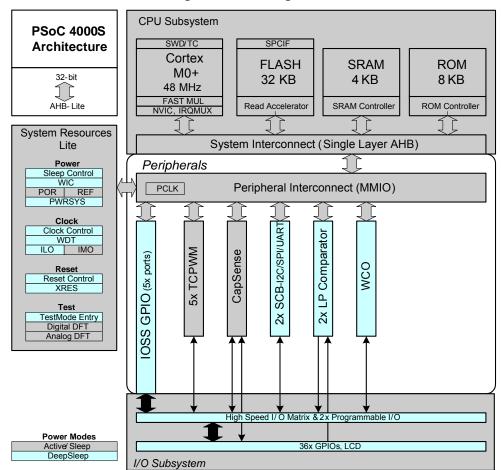


Figure 1. Block Diagram

PSoC 4000S devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware.

The ARM Serial-Wire Debug (SWD) interface supports all programming and debug features of the device.

Complete debug-on-chip functionality enables full-device debugging in the final system using the standard production device. It does not require special interfaces, debugging pods, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The PSoC Creator IDE provides fully integrated programming and debug support for the PSoC 4000S devices. The SWD interface is fully compatible with industry-standard third-party tools. The PSoC 4000S family provides a level of security not possible with multi-chip application solutions or with microcontrollers. It has the following advantages:

- Allows disabling of debug features
- Robust flash protection
- Allows customer-proprietary functionality to be implemented in on-chip programmable blocks

The debug circuits are enabled by default and can be disabled in firmware. If they are not enabled, the only way to re-enable them is to erase the entire device, clear flash protection, and reprogram the device with new firmware that enables debugging. Thus firmware control of debugging cannot be over-ridden without erasing the firmware thus providing security.

Additionally, all device interfaces can be permanently disabled (device security) for applications concerned about phishing attacks due to a maliciously reprogrammed device or attempts to defeat security by starting and interrupting flash programming sequences. All programming, debug, and test interfaces are disabled when maximum device security is enabled. Therefore, PSoC 4000S, with device security enabled, may not be returned for failure analysis. This is a trade-off the PSoC 4000S allows the customer to make.



### Watchdog Timer

A watchdog timer is implemented in the clock block running from the ILO; this allows watchdog operation during Deep Sleep and generates a watchdog reset if not serviced before the set timeout occurs. The watchdog reset is recorded in a Reset Cause register, which is firmware readable.

#### Reset

The PSoC 4000S can be reset from a variety of sources including a software reset. Reset events are asynchronous and guarantee reversion to a known state. The reset cause is recorded in a register, which is sticky through reset and allows software to determine the cause of the reset. An XRES pin is reserved for external reset by asserting it active low. The XRES pin has an internal pull-up resistor that is always enabled.

#### Voltage Reference

The PSoC 4000S reference system generates all internally required references. A 1.2-V voltage reference is provided for the comparator. The IDACs are based on a  $\pm 5\%$  reference.

## Analog Blocks

### Low-power Comparators (LPC)

The PSoC 4000S has a pair of low-power comparators, which can also operate in Deep Sleep modes. This allows the analog system blocks to be disabled while retaining the ability to monitor external voltage levels during low-power modes. The comparator outputs are normally synchronized to avoid metastability unless operating in an asynchronous power mode where the system wake-up circuit is activated by a comparator switch event. The LPC outputs can be routed to pins.

#### Current DACs

The PSoC 4000S has two IDACs, which can drive any of the pins on the chip. These IDACs have programmable current ranges.

#### Analog Multiplexed Buses

The PSoC 4000S has two concentric independent buses that go around the periphery of the chip. These buses (called amux buses) are connected to firmware-programmable analog switches that allow the chip's internal resources (IDACs, comparator) to connect to any pin on the I/O Ports.

## **Programmable Digital Blocks**

The programmable I/O (Smart I/O) block is a fabric of switches and LUTs that allows Boolean functions to be performed in signals being routed to the pins of a GPIO port. The Smart I/O can perform logical operations on input pins to the chip and on signals going out as outputs.

## **Fixed Function Digital**

#### Timer/Counter/PWM (TCPWM) Block

The TCPWM block consists of a 16-bit counter with user-programmable period length. There is a capture register to record the count value at the time of an event (which may be an I/O event), a period register that is used to either stop or auto-reload the counter when its count is equal to the period register, and compare registers to generate compare value signals that are used as PWM duty cycle outputs. The block also provides true and complementary outputs with programmable offset between them to allow use as dead-band programmable complementary PWM outputs. It also has a Kill input to force outputs to a predetermined state; for example, this is used in motor drive systems when an over-current state is indicated and the PWM driving the FETs needs to be shut off immediately with no time for software intervention. There are five TCPWM blocks in the PSoC 4000S.

#### Serial Communication Block (SCB)

The PSoC 4000S has two serial communication blocks, which can be programmed to have SPI, I2C, or UART functionality.

**I<sup>2</sup>C Mode**: The hardware I<sup>2</sup>C block implements a full multi-master and slave interface (it is capable of multi-master arbitration). This block is capable of operating at speeds of up to 400 kbps (Fast Mode) and has flexible buffering options to reduce interrupt overhead and latency for the CPU. It also supports EZI2C that creates a mailbox address range in the memory of the PSoC 4000S and effectively reduces I<sup>2</sup>C communication to reading from and writing to an array in memory. In addition, the block supports an 8-deep FIFO for receive and transmit which, by increasing the time given for the CPU to read data, greatly reduces the need for clock stretching caused by the CPU not having read data on time.

The I<sup>2</sup>C peripheral is compatible with the I<sup>2</sup>C Standard-mode and Fast-mode devices as defined in the NXP I<sup>2</sup>C-bus specification and user manual (UM10204). The I<sup>2</sup>C bus I/O is implemented with GPIO in open-drain modes.

The PSoC 4000S is not completely compliant with the  $I^2C$  spec in the following respect:

GPIO cells are not overvoltage tolerant and, therefore, cannot be hot-swapped or powered up independently of the rest of the I<sup>2</sup>C system.

**UART Mode**: This is a full-feature UART operating at up to 1 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit multiprocessor mode that allows addressing of peripherals connected over common RX and TX lines. Common UART functions such as parity error, break detect, and frame error are supported. An 8-deep FIFO allows much greater CPU service latencies to be tolerated.

**SPI Mode**: The SPI mode supports full Motorola SPI, TI SSP (adds a start pulse used to synchronize SPI Codecs), and National Microwire (half-duplex form of SPI). The SPI block can use the FIFO.



## **Pinouts**

The following table provides the pin list for PSoC 4000S for the 48-pin TQFP, 40-pin QFN, 32-pin QFN, 24-pin QFN, and 25-ball CSP packages. All port pins support GPIO. Pin 11 is a No-Connect in the 48-TQFP.

Table 1.	PSoC	4000S	Pin L	ist
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48	-TQFP	32	2-QFN	2	4-QFN	2	25-CSP		10-QFN
Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name
28	P0.0	17	P0.0	13	P0.0	D1	P0.0	22	P0.0
29	P0.1	18	P0.1	14	P0.1	C3	P0.1	23	P0.1
30	P0.2	19	P0.2					24	P0.2
31	P0.3	20	P0.3					25	P0.3
32	P0.4	21	P0.4	15	P0.4	C2	P0.4	26	P0.4
33	P0.5	22	P0.5	16	P0.5	C1	P0.5	27	P0.5
34	P0.6	23	P0.6	17	P0.6	B1	P0.6	28	P0.6
35	P0.7					B2	P0.7	29	P0.7
36	XRES	24	XRES	18	XRES	B3	XRES	30	XRES
37	VCCD	25	VCCD	19	VCCD	A1	VCCD	31	VCCD
38	VSSD	26	VSSD	20	VSSD	A2	VSS		
39	VDDD	27	VDD	21	VDD	A3	VDD	32	VDDD
40	VDDA	27	VDD	21	VDD	A3	VDD	33	VDDA
41	VSSA	28	VSSA	22	VSSA	A2	VSS	34	VSSA
42	P1.0	29	P1.0					35	P1.0
43	P1.1	30	P1.1					36	P1.1
44	P1.2	31	P1.2	23	P1.2	A4	P1.2	37	P1.2
45	P1.3	32	P1.3	24	P1.3	B4	P1.3	38	P1.3
46	P1.4							39	P1.4
47	P1.5								
48	P1.6								
1	P1.7	1	P1.7	1	P1.7	A5	P1.7	40	P1.7
2	P2.0	2	P2.0	2	P2.0	B5	P2.0	1	P2.0
3	P2.1	3	P2.1	3	P2.1	C5	P2.1	2	P2.1
4	P2.2	4	P2.2					3	P2.2
5	P2.3	5	P2.3					4	P2.3
6	P2.4							5	P2.4
7	P2.5	6	P2.5					6	P2.5
8	P2.6	7	P2.6	4	P2.6	D5	P2.6	7	P2.6
9	P2.7	8	P2.7	5	P2.7	C4	P2.7	8	P2.7
10	VSSD					A2	VSS	9	VSSD
12	P3.0	9	P3.0	6	P3.0	E5	P3.0	10	P3.0
13	P3.1	10	P3.1			D4	P3.1	11	P3.1
14	P3.2	11	P3.2	7	P3.2	E4	P3.2	12	P3.2
16	P3.3	12	P3.3	8	P3.3	D3	P3.3	13	P3.3

# PSoC<sup>®</sup> 4: PSoC 4000S Family Datasheet



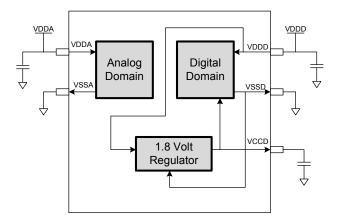
Port/ Pin	Analog	Smart I/O	Alternate Function 1	Alternate Function 2	Alternate Function 3	Deep Sleep 1	Deep Sleep 2
P1.6							scb[0].spi_select3:1
P1.7							
P2.0		prgio[0].io[0]	tcpwm.line[4]:0	csd.comp	tcpwm.tr_in[4]	scb[1].i2c_scl:1	scb[1].spi_mosi:2
P2.1		prgio[0].io[1]	tcpwm.line_compl[4]:0		tcpwm.tr_in[5]	scb[1].i2c_sda:1	scb[1].spi_miso:2
P2.2		prgio[0].io[2]					scb[1].spi_clk:2
P2.3		prgio[0].io[3]					scb[1].spi_select0:2
P2.4		prgio[0].io[4]	tcpwm.line[0]:1				scb[1].spi_select1:1
P2.5		prgio[0].io[5]	tcpwm.line_compl[0]:1				scb[1].spi_select2:1
P2.6		prgio[0].io[6]	tcpwm.line[1]:1				scb[1].spi_select3:1
P2.7		prgio[0].io[7]	tcpwm.line_compl[1]:1			lpcomp.comp[0]:1	
P3.0		prgio[1].io[0]	tcpwm.line[0]:0	scb[1].uart_rx:1		scb[1].i2c_scl:2	scb[1].spi_mosi:0
P3.1		prgio[1].io[1]	tcpwm.line_compl[0]:0	scb[1].uart_tx:1		scb[1].i2c_sda:2	scb[1].spi_miso:0
P3.2		prgio[1].io[2]	tcpwm.line[1]:0	scb[1].uart_cts:1		cpuss.swd_data	scb[1].spi_clk:0
P3.3		prgio[1].io[3]	tcpwm.line_compl[1]:0	scb[1].uart_rts:1		cpuss.swd_clk	scb[1].spi_select0:0
P3.4		prgio[1].io[4]	tcpwm.line[2]:0		tcpwm.tr_in[6]		scb[1].spi_select1:0
P3.5		prgio[1].io[5]	tcpwm.line_compl[2]:0		tcpwm.tr_in[7]		scb[1].spi_select2:0
P3.6		prgio[1].io[6]	tcpwm.line[3]:0		tcpwm.tr_in[8]		scb[1].spi_select3:0
P3.7		prgio[1].io[7]	tcpwm.line_compl[3]:0		tcpwm.tr_in[9]	lpcomp.comp[1]:1	
P4.0	csd.vref_ext			scb[0].uart_rx:0	tcpwm.tr_in[10]	scb[0].i2c_scl:1	scb[0].spi_mosi:0
P4.1	csd.cshieldpads			scb[0].uart_tx:0	tcpwm.tr_in[11]	scb[0].i2c_sda:1	scb[0].spi_miso:0
P4.2	csd.cmodpad			scb[0].uart_cts:0		lpcomp.comp[0]:0	scb[0].spi_clk:0
P4.3	csd.csh_tank			scb[0].uart_rts:0		lpcomp.comp[1]:0	scb[0].spi_select0:0



## Power

The following power system diagram shows the set of power supply pins as implemented for the PSoC 4000S. The system has one regulator in Active mode for the digital circuitry. There is no analog regulator; the analog circuits run directly from the  $V_{DD}$  input.

#### Figure 3. Power Supply Connections



There are two distinct modes of operation. In Mode 1, the supply voltage range is 1.8 V to 5.5 V (unregulated externally; internal regulator operational). In Mode 2, the supply range is  $1.8 \text{ V} \pm 5\%$  (externally regulated; 1.71 to 1.89, internal regulator bypassed).

## Mode 1: 1.8 V to 5.5 V External Supply

In this mode, the PSoC 4000S is powered by an external power supply that can be anywhere in the range of 1.8 to 5.5 V. This range is also designed for battery-powered operation. For example, the chip can be powered from a battery system that starts at 3.5 V and works down to 1.8 V. In this mode, the internal regulator of the PSoC 4000S supplies the internal logic and its output is connected to the V<sub>CCD</sub> pin. The VCCD pin must be bypassed to ground via an external capacitor (0.1  $\mu$ F; X5R ceramic or better) and must not be connected to anything else.

## Mode 2: 1.8 V ±5% External Supply

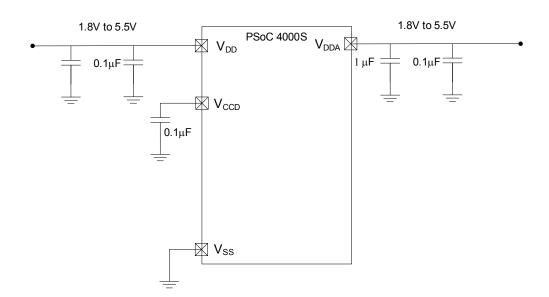
In this mode, the PSoC 4000S is powered by an external power supply that must be within the range of 1.71 to 1.89 V; note that this range needs to include the power supply ripple too. In this mode, the VDD and VCCD pins are shorted together and bypassed. The internal regulator can be disabled in the firmware.

Bypass capacitors must be used from VDDD to ground. The typical practice for systems in this frequency range is to use a capacitor in the 1- $\mu$ F range, in parallel with a smaller capacitor (0.1  $\mu$ F, for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and the bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

An example of a bypass scheme is shown in the following diagram.

## Figure 4. External Supply Range from 1.8 V to 5.5 V with Internal Regulator Active

Power supply bypass connections example





## **Development Support**

The PSoC 4000S family has a rich set of documentation, development tools, and online resources to assist you during your development process. Visit www.cypress.com/go/psoc4 to find out more.

## Documentation

A suite of documentation supports the PSoC 4000S family to ensure that you can find answers to your questions quickly. This section contains a list of some of the key documents.

**Software User Guide**: A step-by-step guide for using PSoC Creator. The software user guide shows you how the PSoC Creator build process works in detail, how to use source control with PSoC Creator, and much more.

**Component Datasheets**: The flexibility of PSoC allows the creation of new peripherals (components) long after the device has gone into production. Component data sheets provide all of the information needed to select and use a particular component, including a functional description, API documentation, example code, and AC/DC specifications.

**Application Notes**: PSoC application notes discuss a particular application of PSoC in depth; examples include brushless DC motor control and on-chip filtering. Application notes often include example projects in addition to the application note document.

**Technical Reference Manual**: The Technical Reference Manual (TRM) contains all the technical detail you need to use a PSoC device, including a complete description of all PSoC registers. The TRM is available in the Documentation section at www.cypress.com/psoc4.

### Online

In addition to print documentation, the Cypress PSoC forums connect you with fellow PSoC users and experts in PSoC from around the world, 24 hours a day, 7 days a week.

### Tools

With industry standard cores, programming, and debugging interfaces, the PSoC 4000S family is part of a development tool ecosystem. Visit us at www.cypress.com/go/psoccreator for the latest information on the revolutionary, easy to use PSoC Creator IDE, supported third party compilers, programmers, debuggers, and development kits.



## **Electrical Specifications**

## Absolute Maximum Ratings

## Table 2. Absolute Maximum Ratings<sup>[1]</sup>

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SID1	V <sub>DDD_ABS</sub>	Digital supply relative to V <sub>SS</sub>	-0.5	I	6		-
SID2	V <sub>CCD_ABS</sub>	Direct digital core voltage input relative to $V_{SS}$	-0.5	-	1.95	V	_
SID3	V <sub>GPIO_ABS</sub>	GPIO voltage	-0.5	-	V <sub>DD</sub> +0.5	1	-
SID4	I <sub>GPIO_ABS</sub>	Maximum current per GPIO	-25	-	25		-
SID5	I <sub>GPIO_injection</sub>	GPIO injection current, Max for V <sub>IH</sub> > V <sub>DDD</sub> , and Min for V <sub>IL</sub> < V <sub>SS</sub>	-0.5	-	0.5	mA	Current injected per pin
BID44	ESD_HBM	Electrostatic discharge human body model	2200	-	-	V	_
BID45	ESD_CDM	Electrostatic discharge charged device model	500	-	-		_
BID46	LU	Pin current for latch-up	-140	-	140	mA	_

## **Device Level Specifications**

All specifications are valid for –40 °C  $\leq$  T<sub>A</sub>  $\leq$  85 °C and T<sub>J</sub>  $\leq$  100 °C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

#### Table 3. DC Specifications

Typical values measured at V<sub>DD</sub> = 3.3 V and 25 °C.

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SID53	V <sub>DD</sub>	Power supply input voltage	1.8	-	5.5		Internally regulated supply
SID255	V <sub>DD</sub>	Power supply input voltage ( $V_{CCD}$ = $V_{DD}$ = $V_{DDA}$ )	1.71	-	1.89	V	Internally unregulated supply
SID54	V <sub>CCD</sub>	Output voltage (for core logic)	-	1.8	-		-
SID55	C <sub>EFC</sub>	External regulator voltage bypass	_	0.1	_	υE	X5R ceramic or better
SID56	C <sub>EXC</sub>	Power supply bypass capacitor	_	1	_	μF	X5R ceramic or better
Active Mode,	V <sub>DD</sub> = 1.8 V to 5.	5 V. Typical values measured at VDD =	3.3 V and	d 25 °C.			
SID10	I <sub>DD5</sub>	Execute from flash; CPU at 6 MHz	-	1.2	2.0		-
SID16	I <sub>DD8</sub>	Execute from flash; CPU at 24 MHz	-	2.4	4.0	mA	-
SID19	I <sub>DD11</sub>	Execute from flash; CPU at 48 MHz	-	4.6	5.9		-
Sleep Mode, V	Sleep Mode, VDDD = 1.8 V to 5.5 V (Regulator on)						
SID22	I <sub>DD17</sub>	I <sup>2</sup> C wakeup WDT, and Comparators on	-	1.1	1.6	mA	6 MHz
SID25	I <sub>DD20</sub>	I <sup>2</sup> C wakeup, WDT, and Comparators on	_	1.4	1.9		12 MHz

Note

Usage above the absolute maximum conditions listed in Table 2 may cause permanent damage to the device. Exposure to Absolute Maximum conditions for extended periods of time may affect device reliability. The Maximum Storage Temperature is 150 °C in compliance with JEDEC Standard JESD22-A103, High Temperature Storage Life. When used below Absolute Maximum conditions but above normal operating conditions, the device may not operate to specification.



GPIO

## Table 5. GPIO DC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SID57	V <sub>IH</sub> <sup>[3]</sup>	Input voltage high threshold	$0.7\times V_{DDD}$	-	-		CMOS Input
SID58	V <sub>IL</sub>	Input voltage low threshold	-	-	$0.3  imes V_{DDD}$		CMOS Input
SID241	V <sub>IH</sub> <sup>[3]</sup>	LVTTL input, V <sub>DDD</sub> < 2.7 V	$0.7\times V_{DDD}$	-	_		_
SID242	V <sub>IL</sub>	LVTTL input, V <sub>DDD</sub> < 2.7 V	-	-	$0.3 \times V_{DDD}$		-
SID243	V <sub>IH</sub> <sup>[3]</sup>	LVTTL input, $V_{DDD} \ge 2.7 \text{ V}$	2.0	-	-		-
SID244	V <sub>IL</sub>	LVTTL input, $V_{DDD} \ge 2.7 \text{ V}$	_	١	0.8	V	-
SID59	V <sub>OH</sub>	Output voltage high level	V <sub>DDD</sub> -0.6	١	_		$I_{OH}$ = 4 mA at 3 V $V_{DDD}$
SID60	V <sub>OH</sub>	Output voltage high level	V <sub>DDD</sub> -0.5	-	-		$I_{OH}$ = 1 mA at 3 V $V_{DDD}$
SID61	V <sub>OL</sub>	Output voltage low level	-	-	0.6		I <sub>OL</sub> = 4 mA at 1.8 V V <sub>DDD</sub>
SID62	V <sub>OL</sub>	Output voltage low level	-	-	0.6		$I_{OL}$ = 10 mA at 3 V V <sub>DDD</sub>
SID62A	V <sub>OL</sub>	Output voltage low level	-	-	0.4		$I_{OL}$ = 3 mA at 3 V $V_{DDD}$
SID63	R <sub>PULLUP</sub>	Pull-up resistor	3.5	5.6	8.5	kΩ	-
SID64	R <sub>PULLDOWN</sub>	Pull-down resistor	3.5	5.6	8.5	K77	-
SID65	IIL	Input leakage current (absolute value)	-	-	2	nA	25 °C, V <sub>DDD</sub> = 3.0 V
SID66	C <sub>IN</sub>	Input capacitance	-	-	7	pF	-
SID67 <sup>[4]</sup>	V <sub>HYSTTL</sub>	Input hysteresis LVTTL	25	40	-		$V_{DDD} \ge 2.7 \text{ V}$
SID68 <sup>[4]</sup>	V <sub>HYSCMOS</sub>	Input hysteresis CMOS	$0.05 \times V_{DDD}$	-	-	mV	V <sub>DD</sub> < 4.5 V
SID68A <sup>[4]</sup>	V <sub>HYSCMOS5V5</sub>	Input hysteresis CMOS	200	I	-		V <sub>DD</sub> > 4.5 V
SID69 <sup>[4]</sup>	I <sub>DIODE</sub>	Current through protection diode to $V_{DD}/V_{SS}$	-	-	100	μA	-
SID69A <sup>[4]</sup>	I <sub>TOT_GPIO</sub>	Maximum total source or sink chip current	-	_	200	mA	-

## Table 6. GPIO AC Specifications

(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SID70	T <sub>RISEF</sub>	Rise time in fast strong mode	2	Ι	12	ns	3.3 V V <sub>DDD</sub> , Cload = 25 pF
SID71	T <sub>FALLF</sub>	Fall time in fast strong mode	2	-	12	115	3.3 V V <sub>DDD</sub> , Cload = 25 pF
SID72	T <sub>RISES</sub>	Rise time in slow strong mode	10	-	60	_	3.3 V V <sub>DDD</sub> , Cload = 25 pF
SID73	T <sub>FALLS</sub>	Fall time in slow strong mode	10	_	60	_	3.3 V V <sub>DDD</sub> , Cload = 25 pF

Notes

3. V<sub>IH</sub> must not exceed V<sub>DDD</sub> + 0.2 V.
 4. Guaranteed by characterization.



## **Analog Peripherals**

## Table 9. Comparator DC Specifications

Spec ID#	Parameter	Description	Min	Тур	Мах	Units	Details/ Conditions
SID84	V <sub>OFFSET1</sub>	Input offset voltage, Factory trim	-	-	±10		-
SID85	V <sub>OFFSET2</sub>	Input offset voltage, Custom trim	-	-	±4	mV	-
SID86	V <sub>HYST</sub>	Hysteresis when enabled	-	10	35		-
SID87	V <sub>ICM1</sub>	Input common mode voltage in normal mode	0	-	V <sub>DDD</sub> -0.1		Modes 1 and 2
SID247	V <sub>ICM2</sub>	Input common mode voltage in low power mode	0	-	V <sub>DDD</sub>	V	-
SID247A	V <sub>ICM3</sub>	Input common mode voltage in ultra low power mode	0	-	V <sub>DDD</sub> -1.15		V <sub>DDD</sub> ≥ 2.2 V at _40 °C
SID88	C <sub>MRR</sub>	Common mode rejection ratio	50	-	_	dB	V <sub>DDD</sub> ≥ 2.7V
SID88A	C <sub>MRR</sub>	Common mode rejection ratio	42	-	-	uБ	$V_{DDD} \le 2.7V$
SID89	I <sub>CMP1</sub>	Block current, normal mode	-	-	400		-
SID248	I <sub>CMP2</sub>	Block current, low power mode	-	-	100	μA	-
SID259	I <sub>CMP3</sub>	Block current in ultra low-power mode	-	6	28	Pr	V <sub>DDD</sub> ≥ 2.2 V at _40 °C
SID90	Z <sub>CMP</sub>	DC Input impedance of comparator	35	-	-	MΩ	-

## Table 10. Comparator AC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SID91	TRESP1	Response time, normal mode, 50 mV overdrive	-	38	110	ns	_
SID258	TRESP2	Response time, low power mode, 50 mV overdrive	-	70	200	115	_
SID92	TRESP3	Response time, ultra-low power mode, 200 mV overdrive	-	2.3	15	μs	V <sub>DDD</sub> ≥ 2.2 V at _40 °C



## CSD

## Table 11. CSD and IDAC Specifications

SPEC ID#	Parameter	Description	Min	Тур	Max	Units	Details / Conditions
SYS.PER#3	VDD_RIPPLE	Max allowed ripple on power supply, DC to 10 MHz	-	-	±50	mV	V <sub>DD</sub> > 2 V (with ripple), 25 °C T <sub>A</sub> , Sensitivity = 0.1 pF
SYS.PER#16	VDD_RIPPLE_1.8	Max allowed ripple on power supply, DC to 10 MHz	-	_	±25	mV	$V_{DD}$ > 1.75V (with ripple), 25 °C T <sub>A</sub> , Parasitic Capaci- tance (C <sub>P</sub> ) < 20 pF, Sensitivity ≥ 0.4 pF
SID.CSD.BLK	ICSD	Maximum block current	-	_	4000	μA	Maximum block current for both IDACs in dynamic (switching) mode including comparators, buffer, and reference generator.
SID.CSD#15	V <sub>REF</sub>	Voltage reference for CSD and Comparator	0.6	1.2	V <sub>DDA</sub> - 0.6	V	V <sub>DDA</sub> - 0.06 or 4.4, whichever is lower
SID.CSD#15A	VREF_EXT	External Voltage reference for CSD and Comparator	0.6		V <sub>DDA</sub> - 0.6	V	V <sub>DDA</sub> - 0.06 or 4.4, whichever is lower
SID.CSD#16	IDAC1IDD	IDAC1 (7-bits) block current	-	-	1750	μA	
SID.CSD#17	IDAC2IDD	IDAC2 (7-bits) block current	-	-	1750	μA	
SID308	VCSD	Voltage range of operation	1.71	-	5.5	V	1.8 V ±5% or 1.8 V to 5.5 V
SID308A	VCOMPIDAC	Voltage compliance range of IDAC	0.6	-	V <sub>DDA</sub> –0.6	V	V <sub>DDA</sub> - 0.06 or 4.4, whichever is lower
SID309	IDAC1DNL	DNL	-1	-	1	LSB	
SID310	IDAC1INL	INL	-2	-	2	LSB	INL is ±5.5 LSB for V <sub>DDA</sub> < 2 V
SID311	IDAC2DNL	DNL	-1	-	1	LSB	
SID312	IDAC2INL	INL	-2	-	2	LSB	INL is $\pm 5.5$ LSB for V <sub>DDA</sub> < 2 V
SID313	SNR	Ratio of counts of finger to noise. Guaranteed by characterization	5	-	-	Ratio	Capacitance range of 5 to 35 pF, 0.1-pF sensitivity. All use cases. V <sub>DDA</sub> > 2 V.
SID314	IDAC1CRT1	Output current of IDAC1 (7 bits) in low range	4.2	-	5.4	μA	LSB = 37.5-nA typ.
SID314A	IDAC1CRT2	Output current of IDAC1(7 bits) in medium range	34	-	41	μA	LSB = 300-nA typ.
SID314B	IDAC1CRT3	Output current of IDAC1(7 bits) in high range	275	-	330	μA	LSB = 2.4-µA typ.
SID314C	IDAC1CRT12	Output current of IDAC1 (7 bits) in low range, 2X mode	8	-	10.5	μA	LSB = 75-nA typ.
SID314D	IDAC1CRT22	Output current of IDAC1(7 bits) in medium range, 2X mode	69	-	82	μA	LSB = 600-nA typ.
SID314E	IDAC1CRT32	Output current of IDAC1(7 bits) in high range, 2X mode	540	-	660	μA	LSB = 4.8-µA typ.
SID315	IDAC2CRT1	Output current of IDAC2 (7 bits) in low range	4.2	-	5.4	μA	LSB = 37.5-nA typ.
SID315A	IDAC2CRT2	Output current of IDAC2 (7 bits) in medium range	34	-	41	μA	LSB = 300-nA typ.
SID315B	IDAC2CRT3	Output current of IDAC2 (7 bits) in high range	275	-	330	μA	LSB = 2.4-µA typ.
SID315C	IDAC2CRT12	Output current of IDAC2 (7 bits) in low range, 2X mode	8	-	10.5	μA	LSB = 75-nA typ.
SID315D	IDAC2CRT22	Output current of IDAC2(7 bits) in medium range, 2X mode	69	-	82	μA	LSB = 600-nA typ.
SID315E	IDAC2CRT32	Output current of IDAC2(7 bits) in high range, 2X mode	540	-	660	μA	LSB = 4.8-µA typ.
SID315F	IDAC3CRT13	Output current of IDAC in 8-bit mode in low range	8	-	10.5	μA	LSB = 37.5-nA typ.



## Table 18. UART DC Specifications<sup>[8]</sup>

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID160	I <sub>UART1</sub>	Block current consumption at 100 Kbps	-	-	55	μA	_
SID161	I <sub>UART2</sub>	Block current consumption at 1000 Kbps	_	_	312	μA	-

## Table 19. UART AC Specifications<sup>[8]</sup>

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID162	F <sub>UART</sub>	Bit rate	-	Ι	1	Mbps	-

## Table 20. LCD Direct Drive DC Specifications<sup>[8]</sup>

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID154	I <sub>LCDLOW</sub>	Operating current in low power mode	-	5	-	μA	$16 \times 4$ small segment disp. at 50 Hz
SID155	C <sub>LCDCAP</sub>	LCD capacitance per segment/common driver	-	500	5000	pF	-
SID156	LCD <sub>OFFSET</sub>	Long-term segment offset	-	20	-	mV	-
SID157	I <sub>LCDOP1</sub>			2	_		$32 \times 4$ segments. 50 Hz. 25 °C
SID158	I <sub>LCDOP2</sub>	LCD system operating current Vbias = 3.3 V	_	2	_	mA	$32 \times 4$ segments. 50 Hz. 25 °C

## Table 21. LCD Direct Drive AC Specifications<sup>[8]</sup>

Spec ID	Parameter	Description	Min	Тур	Max	Units	<b>Details/Conditions</b>
SID159	F <sub>LCD</sub>	LCD frame rate	10	50	150	Hz	_



## SWD Interface

## Table 26. SWD Interface Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	<b>Details/Conditions</b>
SID213	F_SWDCLK1	$3.3~V \le V_{DD} \le 5.5~V$	_	Ι	14	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID214	F_SWDCLK2	$1.71~V \leq V_{DD} \leq 3.3~V$	-	-	7		SWDCLK ≤ 1/3 CPU clock frequency
SID215 <sup>[11]</sup>	T_SWDI_SETUP	T = 1/f SWDCLK	0.25*T	-	_		-
SID216 <sup>[11]</sup>	T_SWDI_HOLD	T = 1/f SWDCLK	0.25*T	-	_	ns	-
SID217 <sup>[11]</sup>	T_SWDO_VALID	T = 1/f SWDCLK	-	-	0.5*T	115	-
SID217A <sup>[11]</sup>	T_SWDO_HOLD	T = 1/f SWDCLK	1	—	_		_

## Internal Main Oscillator

## Table 27. IMO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Тур	Max	Units	<b>Details/Conditions</b>
SID218	I <sub>IMO1</sub>	IMO operating current at 48 MHz	-	-	250	μA	-
SID219	I <sub>IMO2</sub>	IMO operating current at 24 MHz		-	180	μA	_

## Table 28. IMO AC Specifications

Spec ID	Parameter	Description		Тур	Max	Units	Details/Conditions
SID223	F <sub>IMOTOL1</sub>	Frequency variation at 24, 32, and 48 MHz (trimmed)	_	-	±2	%	
SID226	T <sub>STARTIMO</sub>	IMO startup time	-	-	7	μs	-
SID228	T <sub>JITRMSIMO2</sub>	RMS jitter at 24 MHz	_	145	-	ps	-

## Internal Low-Speed Oscillator

## Table 29. ILO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID231 <sup>[11]</sup>	I <sub>ILO1</sub>	ILO operating current	_	0.3	1.05	μA	_

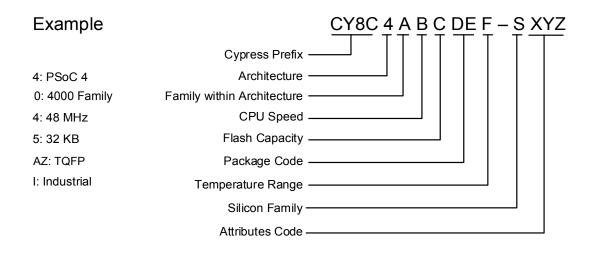
### Table 30. ILO AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	<b>Details/Conditions</b>
SID234 <sup>[11]</sup>	T <sub>STARTILO1</sub>	ILO startup time	-	-	2	ms	-
SID236 <sup>[11]</sup>	T <sub>ILODUTY</sub>	ILO duty cycle	40	50	60	%	_
SID237	F <sub>ILOTRIM1</sub>	ILO frequency range	20	40	80	kHz	-



Field	Description	Values	Meaning
		4	16 KB
с	Flash Capacity	5	32 KB
C		6	64 KB
		7	128 KB
		AX	TQFP (0.8-mm pitch)
		AZ	TQFP (0.5-mm pitch)
DE	Package Code	LQ	QFN
		PV	SSOP
		FN	CSP
F	Temperature Range	I	Industrial
		S	PSoC 4A-S1, PSoC 4A-S2
s	Silicon Family	М	PSoC 4A-M
3	Silicon Fairling	L	PSoC 4A-L
		BL	PSoC 4A-BLE
XYZ	Attributes Code	000-999	Code of feature set in the specific family

The following is an example of a part number:





## Package Diagrams

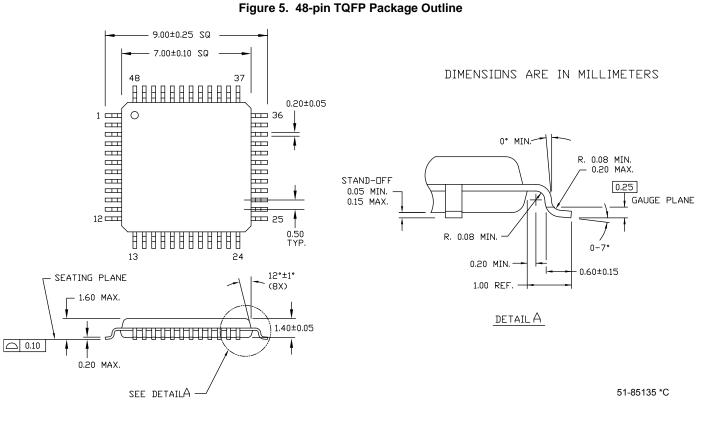


Figure 6. 40-pin QFN Package Outline

TOP VIEW

6.00 ±0.10

PIN 1 DOT

31

30

21

20

±0.10

6.00

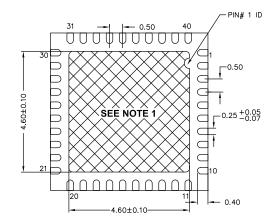
40

Ο

11

0.08

BOTTOM VIEW



NOTES:

10

1. XXX HATCH AREA IS SOLDERABLE EXPOSED PAD

2. REFERENCE JEDEC # MO-248

3. PACKAGE WEIGHT: 68 ±2 mg

4. ALL DIMENSIONS ARE IN MILLIMETERS

001-80659 \*A



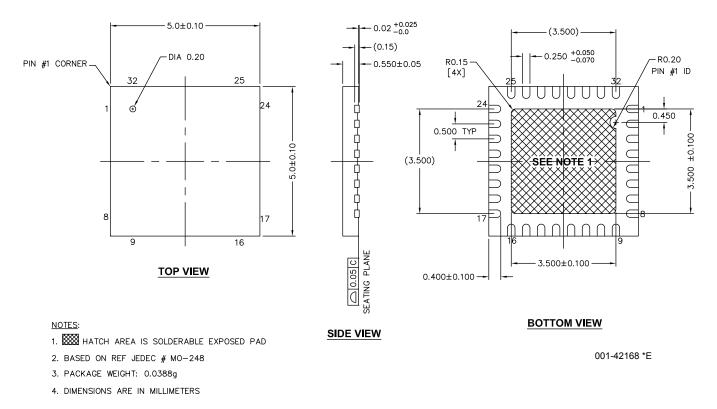
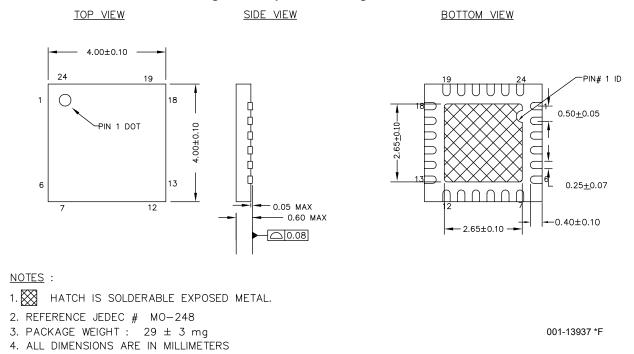


Figure 7. 32-pin QFN Package Outline

Figure 8. 24-pin QFN Package Outline

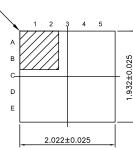


The center pad on the QFN package should be connected to ground (VSS) for best mechanical, thermal, and electrical performance. If not connected to ground, it should be electrically floating and not connected to any other signal.



## Figure 9. 25-Ball WLCSP

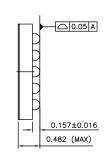


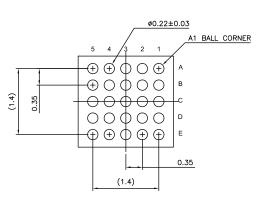


TOP VIEW

<u>SIDE VIEW</u>

## BOTTOM VIEW





ALL DIMENSIONS ARE IN MM JEDEC Publication 95; Design Guide 4.18 002-09957 \*\*



## Acronyms

## Table 40. Acronyms Used in this Document

Acronym	Description
abus	analog local bus
ADC	analog-to-digital converter
AG	analog global
АНВ	AMBA (advanced microcontroller bus architecture) high-performance bus, an ARM data transfer bus
ALU	arithmetic logic unit
AMUXBUS	analog multiplexer bus
API	application programming interface
APSR	application program status register
ARM®	advanced RISC machine, a CPU architecture
ATM	automatic thump mode
BW	bandwidth
CAN	Controller Area Network, a communications protocol
CMRR	common-mode rejection ratio
CPU	central processing unit
CRC	cyclic redundancy check, an error-checking protocol
DAC	digital-to-analog converter, see also IDAC, VDAC
DFB	digital filter block
DIO	digital input/output, GPIO with only digital capabilities, no analog. See GPIO.
DMIPS	Dhrystone million instructions per second
DMA	direct memory access, see also TD
DNL	differential nonlinearity, see also INL
DNU	do not use
DR	port write data registers
DSI	digital system interconnect
DWT	data watchpoint and trace
ECC	error correcting code
ECO	external crystal oscillator
EEPROM	electrically erasable programmable read-only memory
EMI	electromagnetic interference
EMIF	external memory interface
EOC	end of conversion
EOF	end of frame
EPSR	execution program status register
ESD	electrostatic discharge

## Table 40. Acronyms Used in this Document (continued)

Acronym	Description	
ETM	embedded trace macrocell	
FIR	finite impulse response, see also IIR	
FPB	flash patch and breakpoint	
FS	full-speed	
GPIO	general-purpose input/output, applies to a PSoC pin	
HVI	high-voltage interrupt, see also LVI, LVD	
IC	integrated circuit	
IDAC	current DAC, see also DAC, VDAC	
IDE	integrated development environment	
I <sup>2</sup> C, or IIC	Inter-Integrated Circuit, a communications protocol	
lir	infinite impulse response, see also FIR	
ILO	internal low-speed oscillator, see also IMO	
IMO	internal main oscillator, see also ILO	
INL	integral nonlinearity, see also DNL	
I/O	input/output, see also GPIO, DIO, SIO, USBIO	
IPOR	initial power-on reset	
IPSR	interrupt program status register	
IRQ	interrupt request	
ITM	instrumentation trace macrocell	
LCD	liquid crystal display	
LIN	Local Interconnect Network, a communications protocol.	
LR	link register	
LUT	lookup table	
LVD	low-voltage detect, see also LVI	
LVI	low-voltage interrupt, see also HVI	
LVTTL	low-voltage transistor-transistor logic	
MAC	multiply-accumulate	
MCU	microcontroller unit	
MISO	master-in slave-out	
NC	no connect	
NMI	nonmaskable interrupt	
NRZ	non-return-to-zero	
NVIC	nested vectored interrupt controller	
NVL	nonvolatile latch, see also WOL	
opamp	operational amplifier	
PAL	programmable array logic, see also PLD	



## **Document Conventions**

## Units of Measure

## Table 41. Units of Measure

Symbol	Unit of Measure	
°C	degrees Celsius	
dB	decibel	
fF	femto farad	
Hz	hertz	
KB	1024 bytes	
kbps	kilobits per second	
Khr	kilohour	
kHz	kilohertz	
kΩ	kilo ohm	
ksps	kilosamples per second	
LSB	least significant bit	
Mbps	megabits per second	
MHz	megahertz	
MΩ	mega-ohm	
Msps	megasamples per second	
μA	microampere	
μF	microfarad	
μH	microhenry	
μs	microsecond	
μV	microvolt	
μW	microwatt	
mA	milliampere	
ms	millisecond	
mV	millivolt	
nA	nanoampere	
ns	nanosecond	
nV	nanovolt	
Ω	ohm	
pF	picofarad	
ppm	parts per million	
ps	picosecond	
S	second	
sps	samples per second	
sqrtHz	square root of hertz	
V	volt	



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